

REVISIONS

LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
A	Update the boilerplate to the current requirements of MIL-PRF-38535. - jak	08-08-04	Thomas M. Hess
B	Update boilerplate paragraphs to the current MIL-PRF-38535 requirements. Delete class M requirement throughout. - LTG	15-01-28	Thomas M. Hess



REV																				
SHEET																				
REV																				
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REV STATUS	REV	B	B	B	B	B	B	B	B	B	B	B	B	B		
OF SHEETS	SHEET	1	2	3	4	5	6	7	8	9	10	11	12			

PMIC N/A	PREPARED BY Larry T. Gauder	DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990 http://www.landandmaritime.dla.mil			
STANDARD MICROCIRCUIT DRAWING THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE AMSC N/A	CHECKED BY Monica L. Poelking				
	APPROVED BY Monica L. Poelking	MICROCIRCUIT, DIGITAL, BIPOLAR CMOS, EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH THREE-STATE OUTPUTS, TTL COMPATIBLE INPUTS, MONOLITHIC SILICON			
	DRAWING APPROVAL DATE 95-10-12	SIZE A	CAGE CODE 67268	5962-95836	
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1.3 Absolute maximum ratings. 1/ 2/ 3/

Supply voltage range (V_{CC}).....	-0.5 V dc to +7.0 V dc
DC input voltage range (V_{IN}).....	-0.5 V dc to +7.0 V dc <u>4/</u>
DC output voltage range (V_{OUT}).....	-0.5 V dc to +5.5 V dc <u>4/</u>
DC input clamp current (I_{IK}) ($V_{IN} < 0.0$ V).....	-30 mA
DC output current (I_{OL}) (per output).....	+96 mA
Storage temperature range (T_{STG}).....	-65°C to +150°C
Lead temperature (soldering, 10 seconds).....	+300°C
Thermal resistance, junction-to-case (θ_{JC}).....	See MIL-STD-1835
Junction temperature (T_J).....	+175°C
Maximum power dissipation (P_D).....	550 mW

1.4 Recommended operating conditions. 2/ 3/

Supply voltage range (V_{CC}).....	+4.5 V dc to +5.5 V dc
Input voltage range (V_{IN}).....	+0.0 V dc to V_{CC}
Output voltage range (V_{OUT}).....	+0.0 V dc to V_{CC}
Maximum low level input voltage (V_{IL}).....	0.8 V
Minimum high level input voltage (V_{IH}).....	2.0 V
Case operating temperature range (T_C).....	-55°C to +125°C
Maximum high level output current (I_{OH}).....	-12 mA
Maximum low level output current (I_{OL}).....	48 mA
Input clamp current.....	-18 mA

1/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

2/ Unless otherwise noted, all voltages are referenced to GND.

3/ The limits for the parameters specified herein shall apply over the full specified V_{CC} range and case temperature range of -55°C to +125°C.

4/ The input negative and output voltage rating may be exceeded provided that the input and output clamp current rating is observed.

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2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.
MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.
MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <http://quicksearch.dla.mil> or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094).

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 as specified herein, or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V.

3.2.1 Case outlines. The case outlines shall be in accordance with 1.2.4 herein.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.3 Truth table. The truth table shall be as specified on figure 2.

3.2.4 Logic diagram. The logic diagram shall be as specified on figure 3.

3.2.5 Switching waveforms and test circuit. The switching waveforms and test circuit shall be as specified on figure 4.

3.3 Electrical performance characteristics and postirradiation parameter limits. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full case operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.

3.5 Marking. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535.

3.5.1 Certification/compliance mark. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535.

3.6 Certificate of compliance. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). The certificate of compliance submitted to DLA Land and Maritime-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein.

3.7 Certificate of conformance. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 shall be provided with each lot of microcircuits delivered to this drawing.

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TABLE I. Electrical performance characteristics.

Test and MIL-STD-883 test method <u>1/</u>	Symbol	Test conditions <u>2/</u> -55°C ≤ T _C ≤ +125°C +4.5 V ≤ V _{CC} ≤ +5.5 V unless otherwise specified	V _{CC}	Group A subgroups	Limits <u>3/</u>		Unit
					Min	Max	
High level output voltage 3006	V _{OH1}	For all inputs affecting output under test, V _{IN} = V _{IH} = 2.0 V or V _{IL} = 0.8 V I _{OH} = -3.0 mA	4.5 V	1, 2, 3	2.4		V
	V _{OH2}	For all inputs affecting output under test, V _{IN} = V _{IH} = 2.0 V or V _{IL} = 0.8 V I _{OH} = -12 mA	5.0 V	1, 2, 3	2.0		
Low level output voltage 3007	V _{OL}	For all inputs affecting output under test, V _{IN} = V _{IH} = 2.0 V or V _{IL} = 0.8 V I _{OL} = +48 mA	4.5 V	1, 2, 3		0.55	V
Three-state output leakage current high 3021	I _{OZH}	For control inputs affecting outputs under test, V _{IN} = V _{IH} = 2.0 V or V _{IL} = 0.8 V V _{OUT} = 2.7 V	5.5 V	1, 2, 3		50.0	μA
Three-state output leakage current low 3020	I _{OZH}	For control inputs affecting outputs under test, V _{IN} = V _{IH} = 2.0 V or V _{IL} = 0.8 V V _{OUT} = 0.5 V	5.5 V	1, 2, 3		-50.0	μA
Negative input clamp voltage 3022	V _{IC-}	For input under test, I _{IN} = -18 mA	4.5 V	1		-1.2	V
Input current high 3010	I _{IH}	For input under test, V _{IN} = 2.7 V	5.5 V	1, 2, 3		20.0	μA
Input current low 3009	I _{IL}	For input under test, V _{IN} = 0.5 V	5.5 V	1, 2, 3		-0.6	mA
Short circuit output current 3011	I _{OS} <u>4/</u>	V _{OUT} = 0.0 V	0.0 V	1	-100	-225	mA
Quiescent supply current, outputs high 3005	I _{CCH}	V _{IN} = V _{CC} or GND I _{OUT} = 0 A	5.5 V	1, 2, 3		8.0	mA
Quiescent supply current, outputs low 3005	I _{CCL}		5.5 V	1, 2, 3		62.0	mA
Quiescent supply current, outputs three-state 3005	I _{CCZ}		5.5 V	1, 2, 3		8.0	mA
Functional test 3014	<u>5/</u>	V _{IL} = 0.8 V, V _{IH} = 2.0 V Verify output V _O See 4.4.1b	4.5 V	7, 8	L	H	
			5.5 V	7, 8	L	H	
Propagation delay time, CLK to mQ output 3003	t _{PLH} <u>6/</u>	C _L = 50 pF minimum R _L = 500Ω See figure 4	5.0 V	9	2.2	8.6	ns
			4.5 V and 5.5 V	10, 11	2.2	11.2	
	t _{PHL} <u>6/</u>		5.0 V	9	2.8	8.0	ns
			4.5 V and 5.5 V	10, 11	2.8	9.7	

See footnotes at end of table.

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TABLE I. Electrical performance characteristics – Continued.

Test and MIL-STD-883 test method <u>1/</u>	Symbol	Test conditions <u>2/</u> -55°C ≤ T _C ≤ +125°C +4.5 V ≤ V _{CC} ≤ +5.5 V unless otherwise specified	V _{CC}	Group A subgroups	Limits <u>4/</u>		Unit
					Min	Max	
Propagation delay time, output enable, \overline{OE} to mQ output 3003	t_{PZH} <u>6/</u>	$C_L = 50$ pF minimum $R_L = 500\Omega$ See figure 4	5.0 V	9	2.5	8.1	ns
			4.5 V and 5.5 V	10, 11	2.5	10.9	
	t_{PZL} <u>6/</u>		5.0 V	9	3.7	9.2	ns
			4.5 V and 5.5 V	10, 11	3.7	11.3	
Propagation delay time, output disable, \overline{OE} to mQ output 3003	t_{PHZ} <u>6/</u>	$C_L = 50$ pF minimum $R_L = 500\Omega$ See figure 4	5.0 V	9	1.0	7.4	ns
			4.5 V and 5.5 V	10, 11	1.0	8.0	
	t_{PLZ} <u>6/</u>		5.0 V	9	1.3	5.8	ns
			4.5 V and 5.5 V	10, 11	1.3	7.1	
Maximum clock frequency	f_{MAX}	$C_L = 50$ pF minimum $R_L = 500\Omega$ See figure 4	5.0 V	9, 10, 11	77		MHz
Pulse duration, CLK high or low	t_w	$C_L = 50$ pF minimum $R_L = 500\Omega$ See figure 4	5.0 V	9	6.5		ns
Setup time high, data before clock rising	t_{s1} <u>7/</u>		5.0 V	9	4.5		ns
Setup time low, data before clock rising	t_{s2} <u>7/</u>		5.0 V	9	6.0		ns
Hold time, high or low, data after clock rising	t_h <u>7/</u>		5.0 V	9	0.0		ns
			4.5 V and 5.5 V	10, 11	1.0		

- 1/ For tests not listed in the referenced MIL-STD-883, utilize the general test procedure under the conditions listed herein.
- 2/ Each input/output, as applicable, shall be tested at the specified temperature for the specified limits, to the tests in table I herein. Output terminals not designated shall be high level logic, low level logic, or open, except for all I_{CC} tests, where the output terminals shall be open. When performing these tests, the current meter shall be placed in the circuit such that all current flows through the meter. For input terminals not designated, V_{IN} = GND or V_{IN} ≥ 3.0 V.
- 3/ For negative and positive voltage and current values, the sign designates the potential difference in reference to GND and the direction of current flow, respectively; and the absolute value of the magnitude, not the sign, is relative to the minimum and maximum limits, as applicable, listed herein. All devices shall meet or exceed the limits specified in table I if tested at 4.5 V ≤ V_{CC} ≤ 5.5 V.
- 4/ Not more than one output should be tested at one time, and the duration of the test condition should not exceed one second.
- 5/ Tests shall be performed in sequence, attributes data only. Functional tests shall include the truth table and other logic patterns used for fault detection. The test vectors used to verify the truth table shall, at a minimum, test all functions of each input and output. All possible input to output logic patterns per function shall be guaranteed, if not tested, to the truth table in figure 2 herein. Functional tests shall be performed in sequence as approved by the qualifying activity on qualified devices. After incorporating allowable tolerances per MIL-STD-883, V_{IL} = 0.4 V and V_{IH} = 2.4 V. For outputs, L ≤ 0.8 V, H ≥ 2.0 V.
- 6/ For propagation delay tests, all paths must be tested.

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Device type	01
Case outlines	R, S, 2
Terminal number	Terminal symbol
1	\overline{OE}
2	1D
3	2D
4	3D
5	4D
6	5D
7	6D
8	7D
9	8D
10	GND
11	LE
12	8Q
13	7Q
14	6Q
15	5Q
16	4Q
17	3Q
18	2Q
19	1Q
20	V _{CC}

Terminal descriptions	
Terminal symbol	Description
nD (n = 1 to 8)	Data inputs
\overline{OE}	Output enable control (active low)
mQ (m = 1 to 8)	Outputs noninverting
CLK	Clock input (active rising edge)

FIGURE 1. Terminal connections.

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Inputs			Outputs
\overline{OE}	CLK	nD	mQ
L	↑	H	H
L	↑	L	L
L	L or H	X	Q ₀
H	X	X	Z

L = Low voltage level

H = High voltage level

X = Irrelevant

Z = Disabled

Q₀ = The level on mQ before the indicated steady-state input conditions were established.

↑ = Low-to-high transition of the clock

FIGURE 2. Truth table.

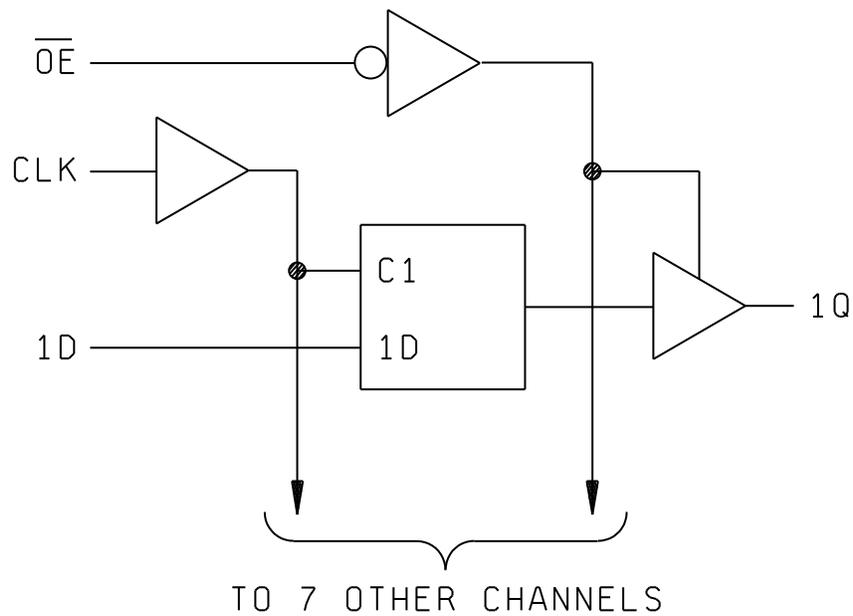


FIGURE 3. Logic diagram.

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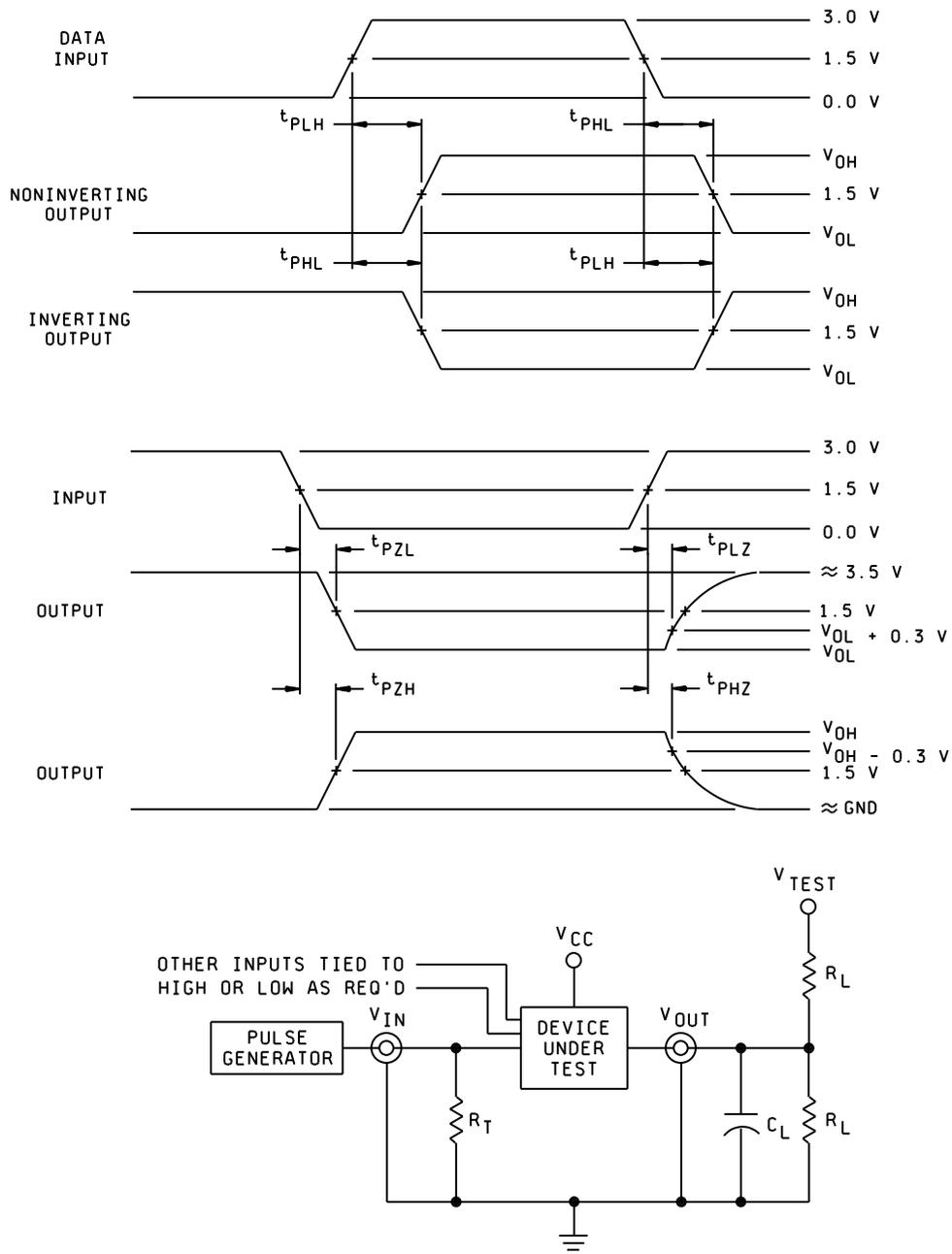


FIGURE 4. Switching waveforms and test circuit.

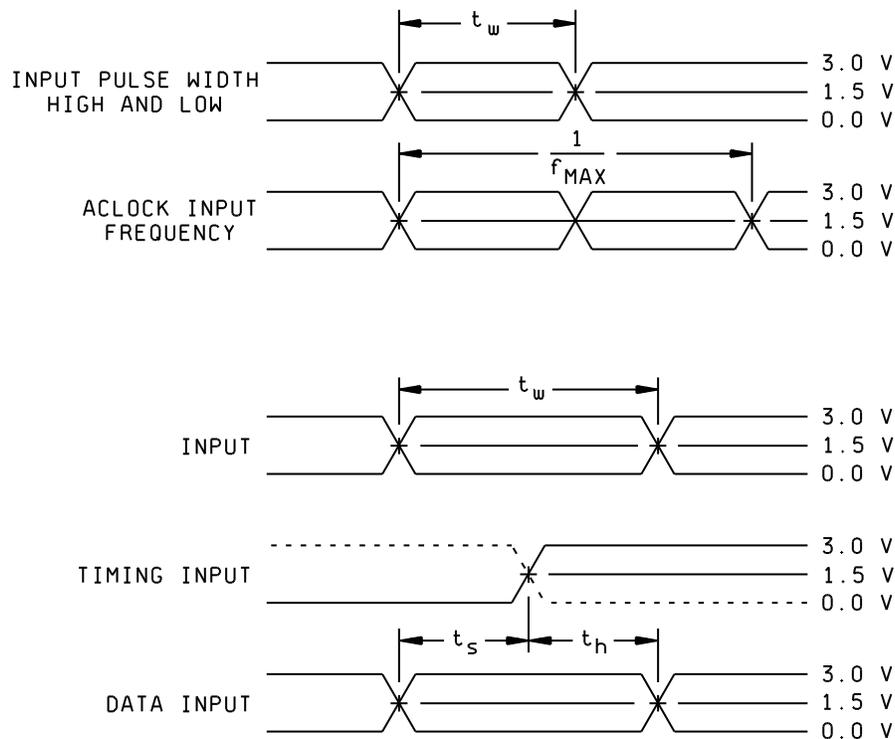
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NOTES:

1. When measuring t_{PLZ} and t_{PZL} : $V_{TEST} = 7.0 \text{ V}$.
2. When measuring t_{PHZ} , t_{PZH} , t_{PLH} , and t_{PLL} : $V_{TEST} = \text{Open}$.
3. The t_{PZL} and t_{PLZ} reference waveform is for the output under test with internal conditions such that the output is at V_{OL} except when disabled by the output enable control. The t_{PZH} and t_{PHZ} reference waveform is for the output under test with internal conditions such that the output is at V_{OH} except when disabled by the output enable control.
4. $C_L = 50 \text{ pF}$ minimum or equivalent (includes test jig and probe capacitance).
5. $R_T = 50\Omega$ or equivalent.
6. $R_L = 500\Omega$ or equivalent.
7. Input signal from pulse generator: $V_{IN} = 0.0 \text{ V}$ to 3.0 V ; $PRR \leq 10 \text{ MHz}$; $t_r \leq 2.5 \text{ ns}$; $t_f \leq 2.5 \text{ ns}$; t_r and t_f shall be measured from 0.3 V to 2.7 V and from 2.7 V to 0.3 V respectively; duty cycle = 50 percent.
8. Timing parameters shall be tested at a minimum input frequency of 1 MHz.
9. The outputs are measured one at a time with one transition per measurement.
10. High = V_{IH} to V_{CC} , Low = V_{IL} to GND.

FIGURE 4. Switching waveforms and test circuit – Continued.

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4. VERIFICATION

4.1 Sampling and inspection. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

4.2 Screening. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection.

4.2.1 Additional criteria for device classes Q and V.

- a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
- b. Interim and final electrical test parameters shall be as specified in table II herein.
- c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.

4.3 Qualification inspection for device classes Q and V. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 Conformance inspection. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections, and as specified herein.

4.4.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. For device classes Q and V, subgroups 7 and 8 shall include verifying the functionality of the device.
- c. Subgroup 4 (C_{IN} and C_{OUT} measurement) shall be measured only for the initial test and after process or design changes which may affect input capacitance.

4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table II herein.

4.4.2.1 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.

4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table II herein.

4.4.4 Group E inspection. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).

- a. End-point electrical parameters shall be as specified in table II herein.
- b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at T_A = +25°C ±5°C, after exposure, to the subgroups specified in table II herein.

4.5 Methods of inspection. Methods of inspection shall be specified as follows:

4.5.1 Voltage and current. Unless otherwise specified, all voltages given are referenced to the microcircuit GND terminal. Currents given are conventional current and positive when flowing into the referenced terminal.

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TABLE II. Electrical test requirements.

Test requirements	Subgroups (in accordance with MIL-PRF-38535, table III)	
	Device class Q	Device class V
Interim electrical parameters (see 4.2)	- - -	1
Final electrical parameters (see 4.2)	<u>1/</u> 1, 2, 3, 7, 8, 9, 10, 11	<u>2/</u> 1, 2, 3, 7, 8, 9, 10, 11
Group A test requirements (see 4.4)	1, 2, 3, 4, 7, 8, 9, 10, 11	1, 2, 3, 4, 7, 8, 9, 10, 11
Group C end-point electrical parameters (see 4.4)	1, 2, 3	1, 2, 3, 7, 8, 9, 10, 11
Group D end-point electrical parameters (see 4.4)	1, 2, 3	1, 2, 3
Group E end-point electrical parameters (see 4.4)	1, 7, 9	1, 7, 9

1/ PDA applies to subgroup 1.

2/ PDA applies to subgroups 1 and 7.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor prepared specification or drawing.

6.2 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.3 Record of users. Military and industrial users should inform DLA Land and Maritime when a system application requires configuration control and which SMD's are applicable to that system. DLA Land and Maritime will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DLA Land and Maritime-VA, telephone (614) 692-8108.

6.4 Comments. Comments on this drawing should be directed to DLA Land and Maritime-VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0540.

6.5 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

6.6 Sources of supply.

6.6.1 Sources of supply for device classes Q and V. Sources of supply for device classes Q and V are listed in MIL-HDBK-103 and QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DLA Land and Maritime-VA and have agreed to this drawing.

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STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 15-01-28

Approved sources of supply for SMD 5962-95836 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DLA Land and Maritime-VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DLA Land and Maritime maintains an online database of all current sources of supply at <http://www.landandmaritime.dla.mil/Programs/Smcr/>.

Standard microcircuit drawing PIN <u>1/</u>	Vendor CAGE number	Vendor similar PIN <u>2/</u>
5962-9583601QRA	01295	SNJ54BCT574J
5962-9583601QSA	01295	SNJ54BCT574W
5962-9583601Q2A	01295	SNJ54BCT574FK

1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.

2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number

01295

Vendor name and address

Texas Instruments Inc.
Semiconductor Group
8505 Forest Ln.
P.O. Box 660199
Dallas, TX 75243
Point of contact: U.S. Highway 75 South
P.O. Box 84, M/S 853
Sherman, TX 75090-9493

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